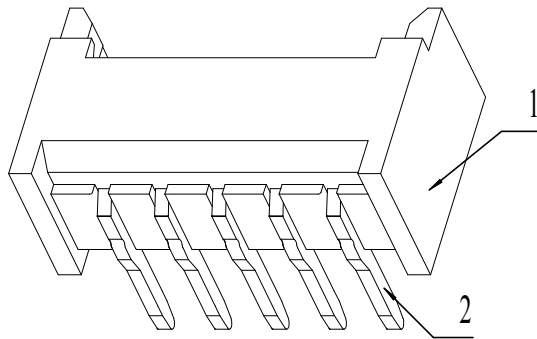
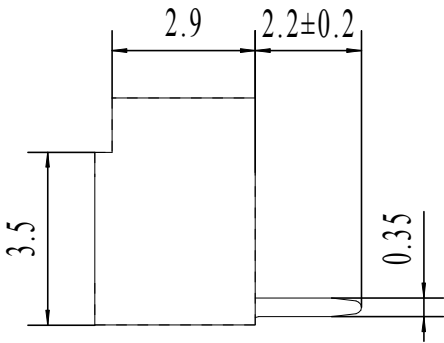
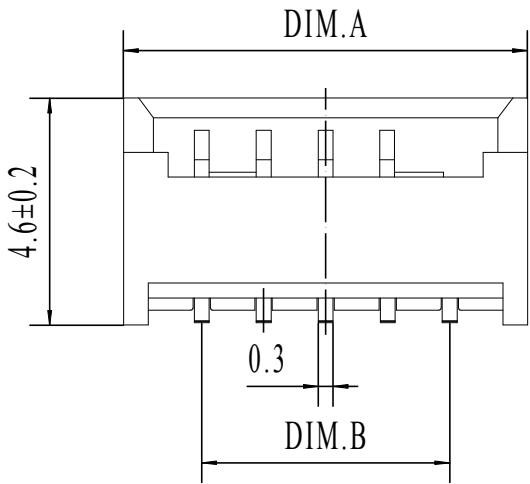
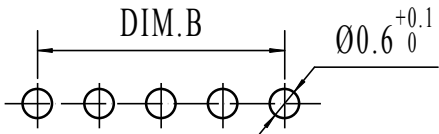
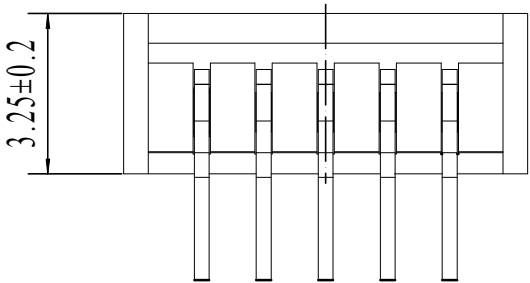


REV.	EC#	DESCRIPTION	DATE	DRAWN	CHECK	APPROVED
1.00		初版发行	2018-04-22			



15	20.65	17.50
14	19.4	16.25
13	18.15	15.00
12	16.9	13.75
11	15.65	12.50
10	14.4	11.25
9	13.15	10.00
8	11.9	8.75
7	10.65	7.50
6	9.4	6.25
5	8.15	5.00
4	6.9	3.75
3	5.65	2.50
2	4.4	1.25
Pin	DIM.A	DIM.B



PCB LAYOUT

适应基板厚度: 1.2mm~1.6mm  
温度范围: -25℃~85℃  
额定电压: 125V AC/DC  
额定电流: 1A  
接触电阻: ≤0.02Ω  
绝缘电阻: ≥100MΩ  
耐 压: 500V AC/minute

技术要求:

- 1) 材质: 见附表;
- 2) 电镀: 见附表;
- 3) 塑件表面平整、光洁、无毛刺、气泡、烧焦、变形、浇口无拉伤、多料或缺料等不良现象;
- 4) 端子表面无氧化、电镀不良等现象。

GENERAL TOLERANCES			
DIM	TOL	DIM	DEG
X		X°	±3.00°
X.X	±0.35	X.X°	±2.00°
X.XX	±0.25	X.XX°	±1.00°
X.XXX	±0.15	X.XXX°	

2	PIN	n PCS	材质: 黄铜, 电镀: 镀亮锡60u~MIN			
1	Housing	1 PCS	材质: PA6T 颜色: 本色或黑色			
NO.	NAME	Q'TY	DESCRIPTION			
深圳市虹成电子有限公司						
DRAW :		2018-04-22	TITLE: 1.25WDIP CONN WAFER		DRAW NAME:  HCZZ0570-4	
DESIGN:		2018-04-22				
CHECK:		2018-04-22	SERIES: 12502 SERIES			
APPROVED		2018-04-22	P/N:		DRAW NO.	
CUSTOMER DRAWING			REV. 1.00	SCALE N/A	UNIT: mm	SHEET: 1/1